

PolarHV™ HiPerFET IXFC 30N60P Power MOSFET IXFR 30N60P

Electrically Isolated Back Surface

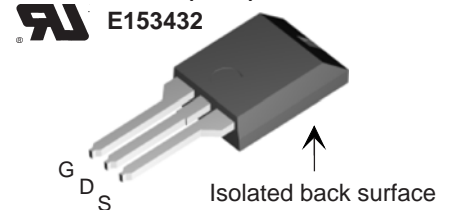
N-Channel Enhancement Mode
Fast Recovery Diode
Avalanche Rated



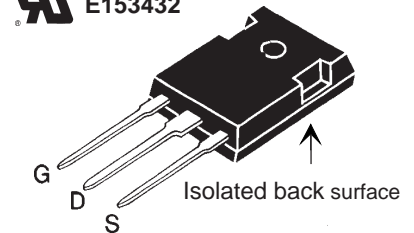
$$\begin{aligned} V_{DSS} &= 600 \text{ V} \\ I_{D25} &= 15 \text{ A} \\ R_{DS(on)} &\leq 250 \text{ m}\Omega \\ t_{rr} &\leq 250 \text{ ns} \end{aligned}$$

| Symbol | Test Conditions | Maximum Ratings | |
|---------------|---|---|------------------|
| | | | |
| V_{DSS} | $T_J = 25^\circ\text{C}$ to 150°C | 600 | V |
| V_{DGR} | $T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1 \text{ M}\Omega$ | 600 | V |
| V_{GSS} | Continuous | ± 30 | V |
| V_{GSM} | Transient | ± 40 | V |
| I_{D25} | $T_C = 25^\circ\text{C}$ | 15 | A |
| I_{DM} | $T_C = 25^\circ\text{C}$, pulse width limited by T_{JM} | 80 | A |
| I_{AR} | $T_C = 25^\circ\text{C}$ | 30 | A |
| E_{AR} | $T_C = 25^\circ\text{C}$ | 50 | mJ |
| E_{AS} | $T_C = 25^\circ\text{C}$ | 1.5 | J |
| dv/dt | $I_S \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 3 \Omega$ | 10 | V/ns |
| P_D | $T_C = 25^\circ\text{C}$ | 166 | W |
| T_J | | -55 ... +150 | $^\circ\text{C}$ |
| T_{JM} | | 150 | $^\circ\text{C}$ |
| T_{stg} | | -55 ... +150 | $^\circ\text{C}$ |
| T_L | 1.6 mm (0.062 in.) from case for 10 s | 300 | $^\circ\text{C}$ |
| V_{ISOL} | 50/60 Hz, RMS, $t = 1$ minute, leads-to-tab | 2500 | V~ |
| F_C | Mounting Force | (IXFC) 11..65 / 2.5..15 (IXFR) 20..120 / 4.5..25 | N/lb N/lb |
| Weight | ISOPLUS220 | 2 | g |
| | ISOPLUS247 | 5 | g |

ISOPLUS220™ (IXFC)
E153432



ISOPLUS247™ (IXFR)
E153432



G = Gate
S = Source
D = Drain

Features

- Silicon chip on Direct-Copper-Bond substrate
- High power dissipation
- Isolated mounting surface
- 2500V electrical isolation
- Low drain to tab capacitance (<30pF)

Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control

Advantages

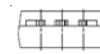
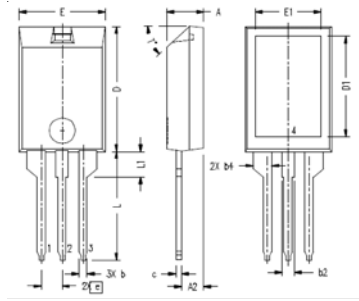
- Easy assembly
- Space savings
- High power density

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified) | Characteristic Values | | |
|--------------|--|-----------------------|------|---------------------------------------|
| | | Min. | Typ. | Max. |
| BV_{DSS} | $V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$ | 600 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 4 \text{ mA}$ | 3.0 | | 5.0 V |
| I_{GSS} | $V_{GS} = \pm 30 \text{ V}$, $V_{DS} = 0$ | | | $\pm 100 \text{ nA}$ |
| I_{DSS} | $V_{DS} = V_{DSS}$ $V_{GS} = 0 \text{ V}$ $T_J = 125^\circ\text{C}$ | | | 25 μA 500 μA |
| $R_{DS(on)}$ | $V_{GS} = 10 \text{ V}$, $I_D = 15 \text{ A}$ Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2\%$ | | | 250 $\text{m}\Omega$ |

| Symbol | Test Conditions | Characteristic Values ($T_J = 25^\circ\text{C}$ unless otherwise specified) | | |
|--------------|---|---|------|--------------------|
| | | Min. | Typ. | Max. |
| g_{fs} | $V_{DS} = 20\text{ V}; I_D = 15\text{ A}$, pulse test | 15 | 27 | S |
| C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$ | | 3820 | pF |
| C_{oss} | | | 360 | pF |
| C_{rss} | | | 28 | pF |
| $t_{d(on)}$ | $V_{GS} = 10\text{ V}, V_{DS} = V_{DSS}, I_D = 15\text{ A}$ $R_G = 3\ \Omega$ (External) | | 22 | ns |
| t_r | | | 20 | ns |
| $t_{d(off)}$ | | | 75 | ns |
| t_f | | | 25 | ns |
| $Q_{g(on)}$ | $V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 15\text{ A}$ | | 85 | nC |
| Q_{gs} | | | 26 | nC |
| Q_{gd} | | | 28 | nC |
| R_{thJC} | | | 0.75 | $^\circ\text{C/W}$ |
| R_{thCS} | | 0.21 | | $^\circ\text{C/W}$ |

Source-Drain Diode **Characteristic Values**
($T_J = 25^\circ\text{C}$ unless otherwise specified)

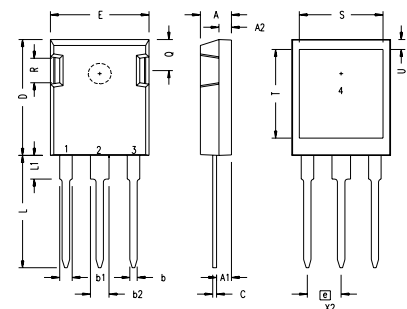
| Symbol | Test Conditions | Min. | Typ. | Max. |
|----------|---|------|------|---------------|
| I_S | $V_{GS} = 0\text{ V}$ | | | 30 A |
| I_{SM} | Repetitive | | | 80 A |
| V_{SD} | $I_F = I_S, V_{GS} = 0\text{ V}$, Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$ | | | 1.5 V |
| t_{rr} | $I_F = 25\text{ A}, -di/dt = 100\text{ A}/\mu\text{s}$ $V_R = 100\text{ V}; V_{GS} = 0\text{ V}$ | | | 200 ns |
| I_{RM} | | | 8 | A |
| Q_{RM} | | | 0.6 | μC |

ISOPLUS220 (IXFC) Outline


Note:
Bottom heatsink (Pin 4) is electrically isolated from Pin 1, 2, or 3.

| SYM | INCHES | | MILLIMETERS | |
|-----|------------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .157 | .197 | 4.00 | 5.00 |
| A2 | .098 | .118 | 2.50 | 3.00 |
| b | .035 | .051 | 0.90 | 1.30 |
| b2 | .049 | .065 | 1.25 | 1.65 |
| b4 | .093 | .100 | 2.35 | 2.55 |
| c | .028 | .039 | 0.70 | 1.00 |
| D | .591 | .630 | 15.00 | 16.00 |
| D1 | .472 | .512 | 12.00 | 13.00 |
| E | .394 | .433 | 10.00 | 11.00 |
| E1 | .295 | .335 | 7.50 | 8.50 |
| e | .100 BASIC | | 2.55 BASIC | |
| L | .512 | .571 | 13.00 | 14.50 |
| L1 | .118 | .138 | 3.00 | 3.50 |
| T* | | | 42.5* | 47.5* |

IXYS CO 0177 R0

ISOPLUS247 (IXFR) Outline


| SYM | INCHES | | MILLIMETERS | |
|-----|----------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .190 | .205 | 4.83 | 5.21 |
| A1 | .090 | .100 | 2.29 | 2.54 |
| A2 | .075 | .085 | 1.91 | 2.16 |
| b | .045 | .055 | 1.14 | 1.40 |
| b1 | .075 | .084 | 1.91 | 2.13 |
| b2 | .115 | .123 | 2.92 | 3.12 |
| C | .024 | .031 | 0.61 | 0.80 |
| D | .819 | .840 | 20.80 | 21.34 |
| E | .620 | .635 | 15.75 | 16.13 |
| e | .215 BSC | | 5.45 BSC | |
| L | .780 | .800 | 19.81 | 20.32 |
| L1 | .150 | .170 | 3.81 | 4.32 |
| Q | .220 | .244 | 5.59 | 6.20 |
| R | .170 | .190 | 4.32 | 4.83 |
| S | .520 | .540 | 13.21 | 13.72 |
| T | .620 | .640 | 15.75 | 16.26 |
| U | .065 | .080 | 1.65 | 2.03 |

- 1 - GATE
- 2 - DRAIN (COLLECTOR)
- 3 - SOURCE (EMITTER)
- 4 - NO CONNECTION

NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-247AD except screw hole.

IXYS reserves the right to change limits, test conditions, and dimensions.

| | | | | | | | | |
|--|-----------|-----------|-----------|-----------|--------------|--------------|-------------|--------------|
| IXYS MOSFETs and IGBTs are covered by | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 |
| one or more of the following U.S. patents: | 4,850,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123 B1 | 6,534,343 | 6,710,405B2 | 6,759,692 |
| | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 |

Fig. 1. Output Characteristics
@ 25°C

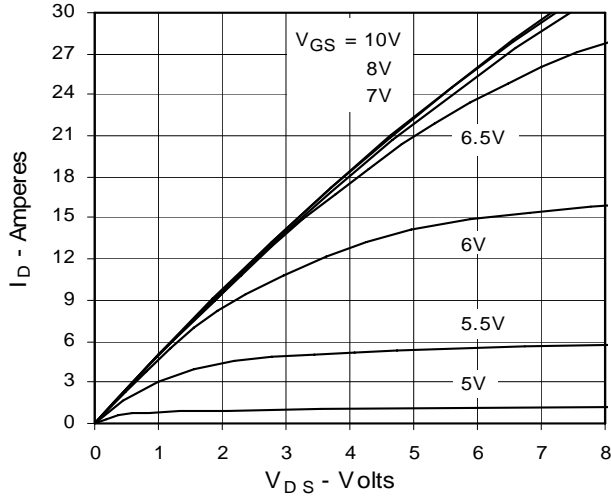


Fig. 2. Extended Output Characteristics
@ 25°C

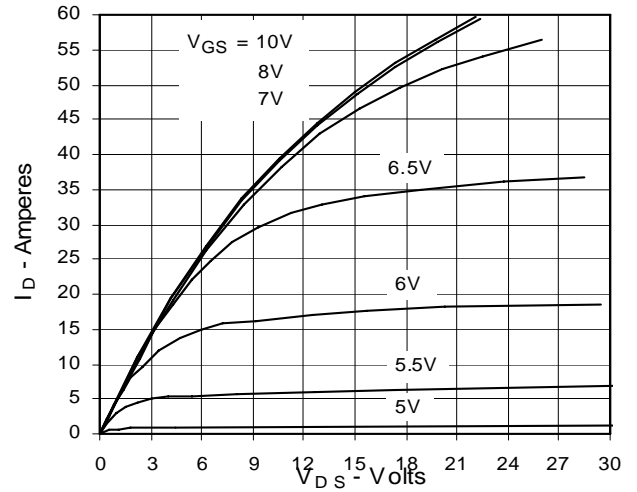


Fig. 3. Output Characteristics
@ 125°C

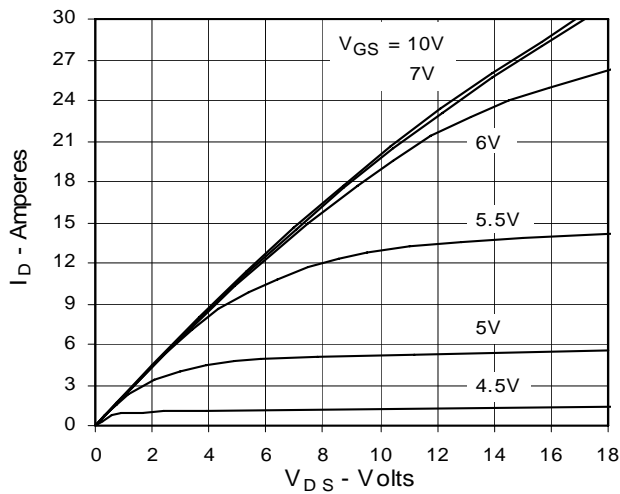


Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 15A$ Value vs. Junction Temperature

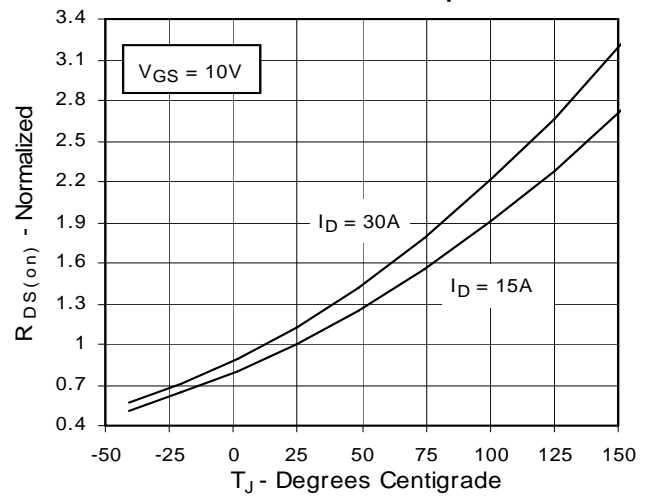


Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 15A$ Value vs. Drain Current

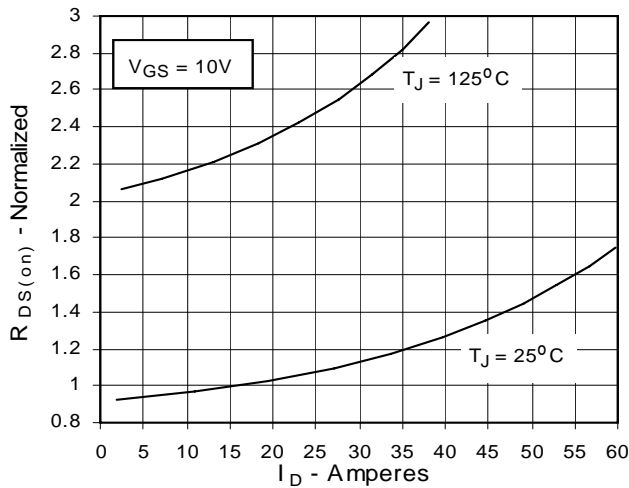


Fig. 6. Drain Current vs. Case Temperature

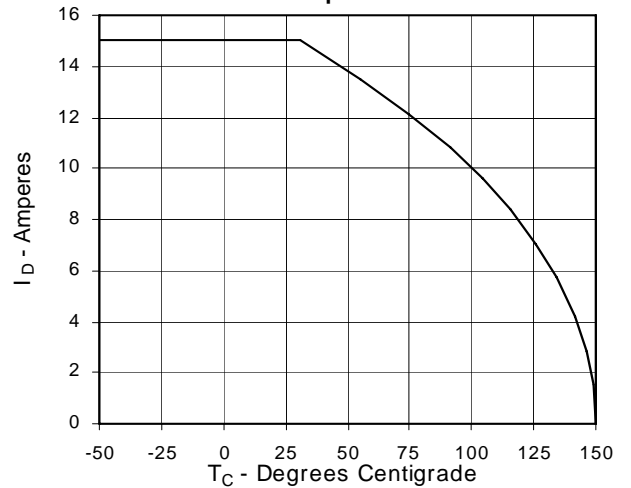


Fig. 7. Input Admittance

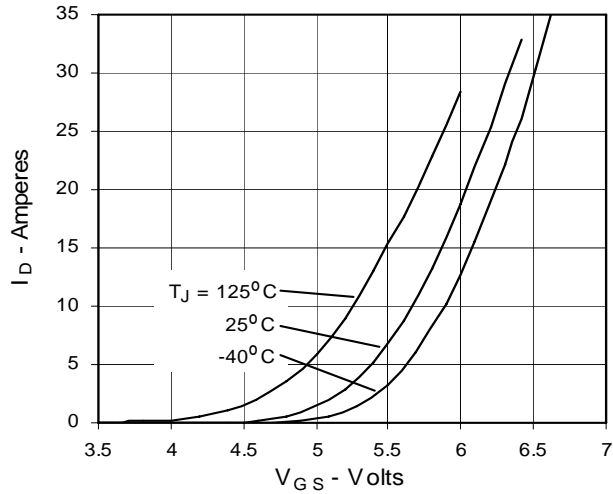


Fig. 8. Transconductance

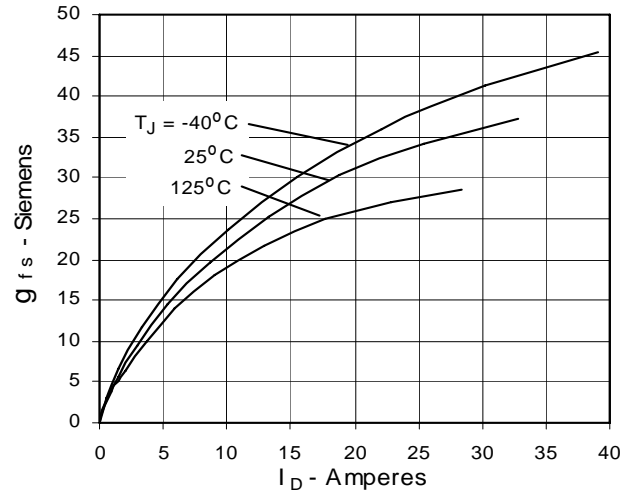


Fig. 9. Source Current vs. Source-To-Drain Voltage

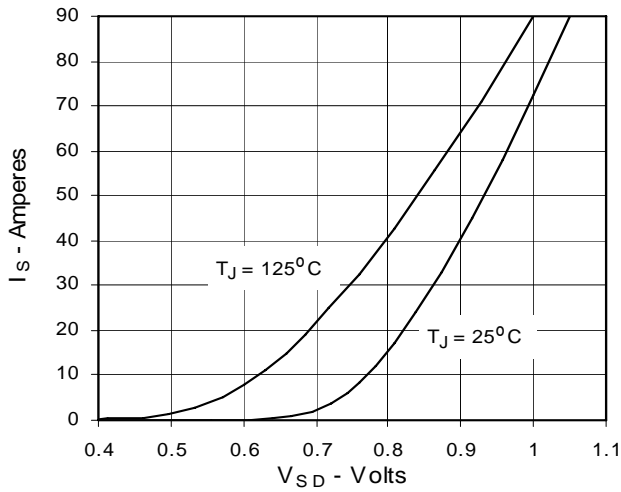


Fig. 10. Gate Charge

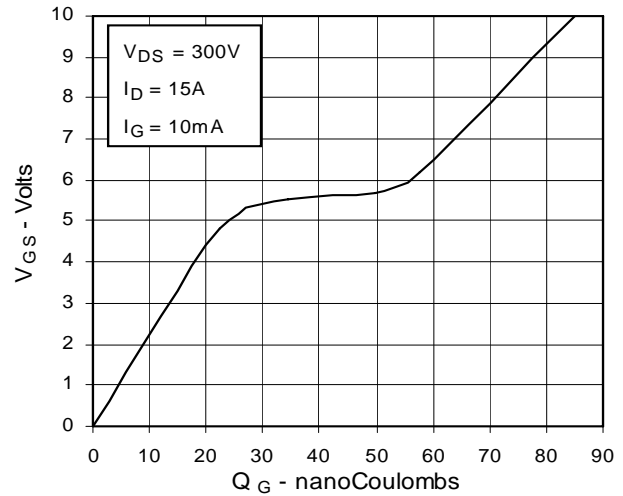


Fig. 11. Capacitance

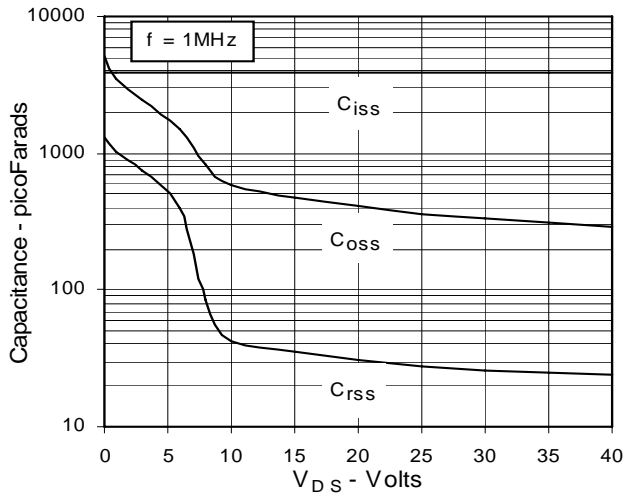
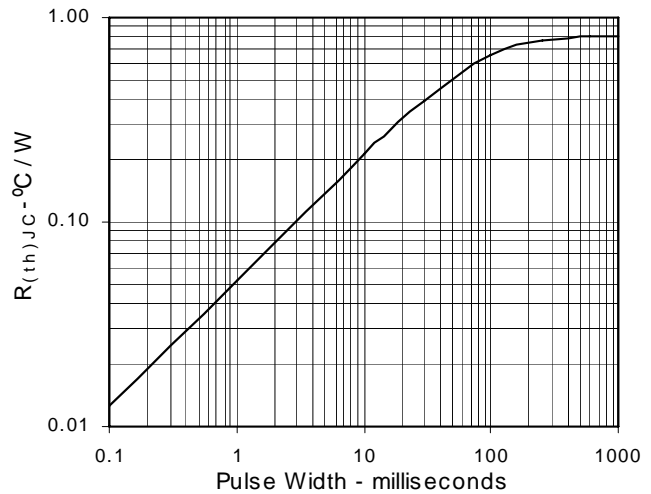


Fig. 12. Maximum Transient Thermal Resistance



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